

APPLICATION DATA SHEET

Electronic Version 0.0.11

Stylesheet Version: 1.0

Publication Filing Type: new-utility

Application Type: utility

Title of Invention: SOLDER PASTE PRINTING METHOD AND APPARATUS FOR PRINTING
SOLDER PASTE ON A BOARD ON WHICH WIRING PATTERNS ARE
FORMED

Legal Representative:

Attorney or Agent: Paul J. Esatto, Jr.

Registration Number: 30749

Customer Number Correspondence Address: 23389



Foreign Priority:

2001-166910 JP 2001-06-01 Priority Claimed

INVENTOR(s):

Primary Citizenship: Japanese

Given Name: Hiroshi

Family Name: Sakai

Residence City: Tokyo

Residence Country: JP

Address: c/o NEC Corporation
7-1, Shiba 5-chome, Minato-ku
Tokyo, JP

Primary Citizenship: Japanese

Given Name: Motoji

Family Name: Suzuki

Residence City: Tokyo

Residence Country: JP

Address: c/o NEC Corporation

7-1, Shiba 5-chome, Minato-ku
Tokyo , JP

Primary Citizenship: Japanese
Given Name: Makoto
Family Name: Igarashi
Residence City: Niigata
Residence Country: JP
Address: 2701, Togawa, Settaya, Nagaoka-shi
Niigata , JP

Primary Citizenship: Japanese
Given Name: Akihiro
Family Name: Tanaka
Residence City: Niigata
Residence Country: JP
Address: 3335-2, Shimononaka, Sanwamura, Nakakubiki-gun
Niigata , JP